

2011 Electronics Packaging Symposium: September 29 – 30, 2011

Technology Advances in Small Scale Systems and Microelectronic Packaging

The 2011 Annual Electronics Packaging Symposium will be held September 29 - 30, 2011 at Binghamton University in Binghamton, New York. The symposium is sponsored by the Integrated Electronics Engineering Center, a New York State Center for Advanced Technology at Binghamton University; General Electric Global Research Center; and the IEEE Component, Packaging and Manufacturing Society. The session topics include Thermal Management, 3-D Packaging, Sensors/MEMs, Power Electronics, Packaging for Harsh Environments, Interconnects, Miniaturization, and Flexible/Printed Electronics.

More information is available at:

<http://www2.binghamton.edu/s3ip/education/symposium2011/index.html>.